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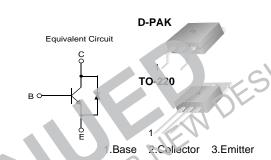


May 2024

# **KSC5402D/KSC5402DT NPN Silicon Transistor, Planar Silicon Transistor**

#### **Features**

- High Voltage High Speed Power Switch Application
- Wide Safe Operating Area
- Built-in Free Wheeling Diode
- Suitable for Electronic Ballast Application
- Small Variance in Storage Time
- Two Package Choices; D-PAK or TO-220



### Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{CBO}$	Collector-Base Voltage	000	V
$V_{CEO}$	Collector-Emitter Voltage	450	V
$V_{EBO}$	Emitter-Base Voltage	12	V
I <sub>C</sub>	Colle or Current (DC)	2	Α
I <sub>CP</sub>	"Collector Current (Puise)	5	Α
I <sub>B</sub>	Base Current (DC)	1	А
IBP	*Base Current (Pulse)	2	Α
Pc	Power Dissipation(T <sub>C</sub> -25°C) : D-PAK*	30	W
	: TO-220	50	W
TJ	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	- 65 to 150	°C

<sup>\*</sup> Pulse Test: Pulse Width=5ms, Duty Cycle<10%

### Thermal Characteristics TA=25°C unless otherwise noted

Symbol	Parameter		Rat	Units	
			TO-220	D-PAK	
$R_{ heta JC}$	Thermal Resistance Junction to Case		2.5	4.17*	°C/W
$R_{\theta JA}$		Junction to Ambient	62.5	50	°C/W
TL	Maximum Lead Temperature for Soldering Purpose ; 1/8" from Case for 5 Seconds		270	270	°C

<sup>\*</sup> Mounted on 1" square PCB (FR4 ro G-10 Material)

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## **Electrical Characteristics** $T_A$ =25°C unless otherwise noted

Symbol	Parameter	Test Condition		Min.	Тур.	Max.	Units
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	I <sub>C</sub> =1mA, I <sub>E</sub> =0		1000	1090		V
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> =5mA, I <sub>B</sub> =0		450	525		V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E=1$ mA, $I_C=0$		12	14		V
I <sub>CES</sub>	Collector Cut-off Current	V <sub>CES</sub> =1000V, I <sub>EB</sub> =0	T <sub>A</sub> =25°C		0.03	100	μΑ
			T <sub>A</sub> =125°C		1.2	500	μΑ
I <sub>CEO</sub>	Collector Cut-off Current	$V_{CE}$ =450V, $V_{B}$ =0	T <sub>A</sub> =25°C		0.3	100	μΑ
			T <sub>A</sub> =125°C		15	500	μΑ
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{EB}$ =10V, $I_{C}$ =0			0.01	100	μΑ
h <sub>FE</sub>	DC Current Gain	$V_{CE}$ =1V, $I_{C}$ =0.4A	T <sub>A</sub> =25°C	14	29		10.
			T <sub>A</sub> =125°C	8	17		
		V <sub>CE</sub> =1V, I <sub>C</sub> =1A	T <sub>A</sub> =25°C	6	9		
			T <sub>A</sub> =125°C	4	6		
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	I <sub>C</sub> =0.4, I <sub>B</sub> =0.04A	T <sub>A</sub> =25°C	-0	0.25	0.6	V
			T <sub>A</sub> =125°C	0,	0.4	1.0	V
		I <sub>C</sub> =1A, I <sub>B</sub> =0.2A	T <sub>A</sub> =25°C		0.3	0.75	V
			Γ <sub>A</sub> =125°C	103	0.65	1.2	V
V <sub>BE</sub> (sat)	Base-Emitter Saturation Voltage	I <sub>C</sub> =0.4A, I <sub>B</sub> =0.04A	Γ <sub>A</sub> =25°C	0, 4	0.78	1.0	V
			T <sub>A</sub> =125°C	76	0.65	0.9	V
		W-11/1 31/1	T <sub>A</sub> =25°C	.0	0.85	1.1	V
			T <sub>A</sub> =125°C		0.75	1.0	V
C <sub>ib</sub>	Input Capacitance	V <sub>EB</sub> =8V, I <sub>C</sub> =0, f=1MHz	2		330	500	pF
C <sub>ob</sub>	Output Capacitance	V <sub>CB</sub> =10V, I <sub>E</sub> =0, f=1MHz			35	100	pF
f <sub>T</sub>	Current Gain Bandwidth Product	1 <sub>C</sub> -0.5A, V <sub>CE</sub> =10V			11		MHz
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> =1A	T <sub>A</sub> =25°C		0.86	1.5	V
	19 19 19 19 19 19 19 19 19 19 19 19 19 1	I <sub>F</sub> =0.2A	T <sub>A</sub> =25°C		0.75	1.2	V
	ICE LEAGE		T <sub>A</sub> =125°C		0.6		V
	IN OLYS	I <sub>F</sub> =0.4A	T <sub>A</sub> =25°C		0.8	1.3	V
	7		T <sub>A</sub> =125°C		0.65		V

### $\textbf{Electrical Characteristics} \hspace{0.1cm} \text{(Continued)} \hspace{0.1cm} \textbf{T}_{A} = 25 ^{\circ} \textbf{C} \hspace{0.1cm} \text{unless otherwise noted}$

Symbol	Parameter	Test Condition		Min.	Тур.	Max.	Units
t <sub>fr</sub>	Diode Froward Recvery Time (di/dt=10A/μs)	I <sub>F</sub> =0.2A I <sub>F</sub> =0.4A I <sub>F</sub> =1A			540 520 480		ns ns ns
V <sub>CE</sub> (DSAT)	Dynamic Saturation Voltage	I <sub>C</sub> =0.4A, I <sub>B1</sub> =40mA V <sub>CC</sub> =300V	@ 1μs		7.5		V
			@ 3μs		2.5		V
		I <sub>C</sub> =1A, I <sub>B1</sub> =200mA	@ 1μs		11.5		>
		V <sub>CC</sub> =300	@ 3μs		1.5		V
RESISTIVE	LOAD SWITCHING (D.C $\leq$ 10%, F	Pulse Width=20μs)					
t <sub>ON</sub>	Turn On Time	I <sub>C</sub> =1A,	T <sub>A</sub> =25°C		110	150	ns
		I <sub>B1</sub> =200mA, I <sub>B2</sub> =150mA,	T <sub>A</sub> =125°C		135		ns
t <sub>OFF</sub>	Turn Off Time	V <sub>CC</sub> =300V,	T <sub>A</sub> =25°C	0.95		1.25	μς
		$R_L = 300\Omega$	T <sub>A</sub> =125°C		1.4		μS
INDUCTIVE	LOAD SWITCHING (V <sub>CC</sub> =15V)					70	
t <sub>STG</sub>	Storage Time	I <sub>C</sub> =0.4A,	T <sub>A</sub> =25°C		0.56	0.65	μS
		I <sub>B1</sub> =40mA,	T <sub>A</sub> =125°C		0.7		μS
t <sub>F</sub>	Fall Time	I <sub>B2</sub> =200mA, Vz=300V,	T <sub>A</sub> =25°C	06	60	175	ns
		L <sub>C</sub> =200H	T <sub>A</sub> =125°C	Ó	75	70	ns
t <sub>C</sub>	Cross-over Time		T <sub>A</sub> = 25°C	G	90	175	ns
			Γ <sub>Λ</sub> =125°C		90		ns
t <sub>STG</sub>	Storage Time	I <sub>C</sub> =0.8A,	Γ <sub>A</sub> =25°C		$n_{i}$	2.75	μS
		I <sub>B1</sub> =100mA, I <sub>B2</sub> =160mA,	T <sub>A</sub> =125°C	OL	3		μS
t <sub>F</sub>	Fall Time	Vz=30€V.	T <sub>A</sub> =25°C		110	175	ns
		L <sub>C</sub> = 200H	$T_A=125^{\circ}C$		180		ns
t <sub>C</sub>	Cross-over Time	0 100	T <sub>A</sub> =25°C		125	350	ns
			T <sub>A</sub> =125°C		185		ns
t <sub>STG</sub>	Storage Time	I <sub>C</sub> = 1A,	T <sub>A</sub> =25°C		1.1	1.2	μS
	10/0	I <sub>B1</sub> =200.mA, I <sub>B2</sub> =500mA,	T <sub>A</sub> =125°C		1.35		μS
t <sub>F</sub>	Fall Time	ν <sub>7</sub> = 300V,	T <sub>A</sub> =25°C		105	150	ns
	12 2 2	¹ <sub>-C</sub> =200μH	T <sub>A</sub> =125°C		75		ns
tC	Cross-over Time		T <sub>A</sub> =25°C		125	150	ns
	N. K.OK		T <sub>A</sub> =125°C		100		ns

### **Typical Performance Characteristics**

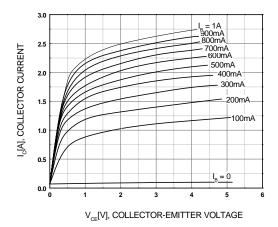


Figure 1. Static Characteristic

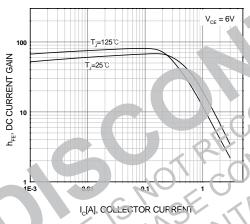


Figure 3. DC current Gain

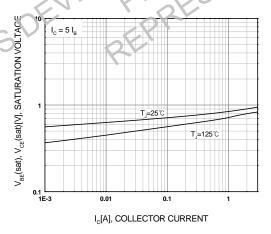


Figure 5. Base-Emitter Saturation Voltage

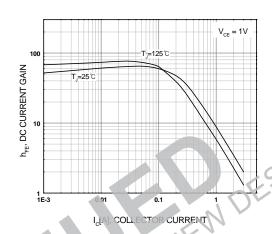


Figure 2. DC current Gain

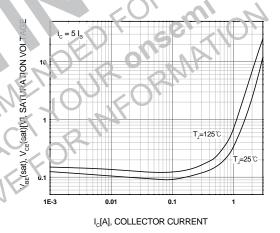


Figure 4. Collector-Emitter Saturation Voltage

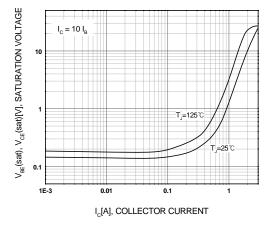


Figure 6. Collector-Emitter Saturation Voltage

### **Typical Performance Characteristics** (Continued)

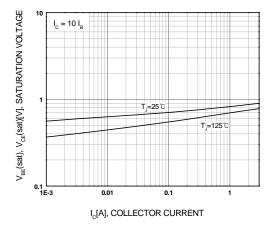
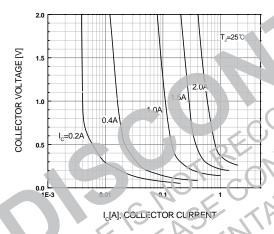


Figure 7. Base-Emitter Saturation Voltage



gure 9. Typical Collector Saturation Region

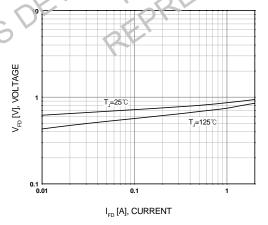


Figure 11. Diode Forward Voltage

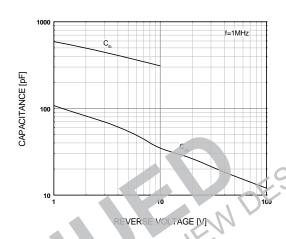


Figure 8. Collector Output Capacitance

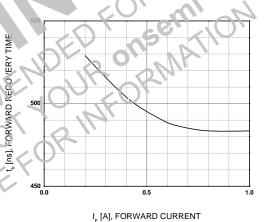


Figure 10. Forward Recovery Time

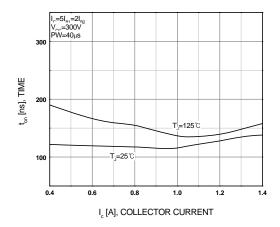


Figure 12. Resistive Switching Time, ton

### Typical Performance Characteristics (Continued)

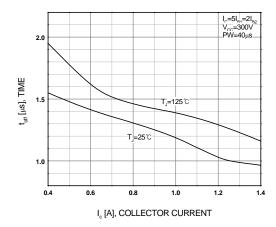


Figure 13. Resistive Switching Time, toff

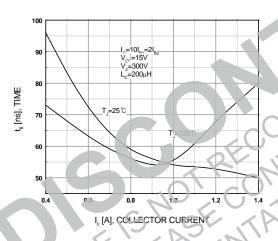


Figure 15. Inductive Switching Time, tfi

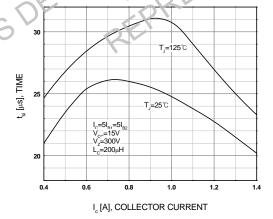


Figure 17. Inductive Switching Time, t<sub>si</sub>

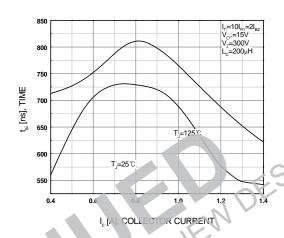


Figure 14. Inductive Switching Time, tsi

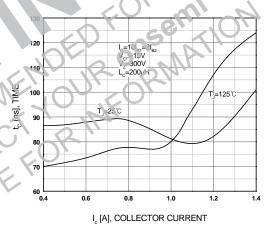


Figure 16. Inductive Switching Time, t<sub>c</sub>

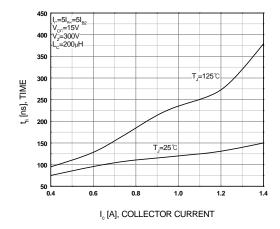


Figure 18. Inductive Switching Time, tfi

### **Typical Performance Characteristics** (Continued)

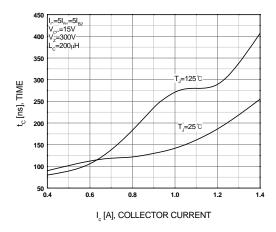


Figure 19. Inductive Switching Time,  $t_c$ 

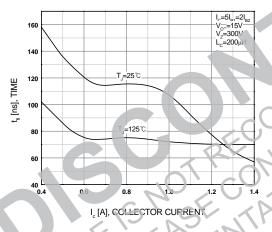


Figure 21. Inductive Switching Time, tfi

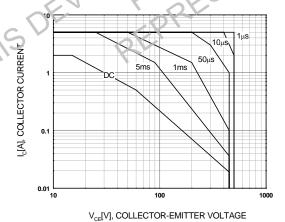


Figure 23. Forward Bias Safe Operating Area

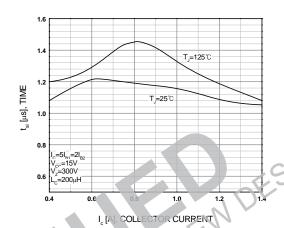


Figure 20. Inductive Switching Time, tsi

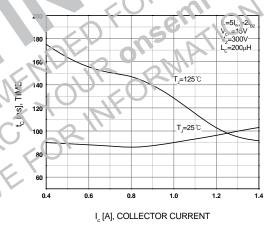


Figure 22. Inductive Switching Time, t<sub>c</sub>

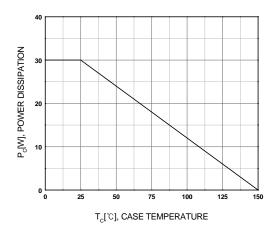


Figure 24. Power Derating

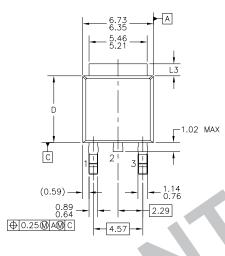
# **Physical Dimension** TO-220 4.50 ±0.20 9.90 ±0.20 (8.70) $1.30 \pm 0.10$ 2.80 ±0.10 (1.70) Ø3.60 ±0.10 (3.70)9.20 ±0.20 .08 ±0.20 $0.50^{\,+0.10}_{\,-0.05}$ 2.40 ±0.20 2.54T\'P [2.54 ±0.20] 2.541 YP [2.54 ±0 20]

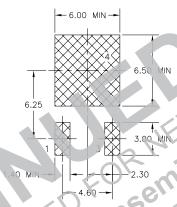
Dimensions in Millimeters

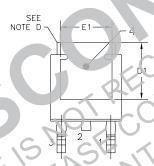
10.00 ±0.20

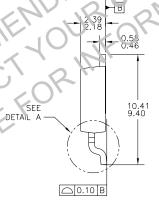
### Physical Dimension (Continued)

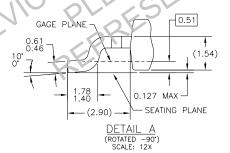
### **D-PAK**











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  A) ALL DIMENSIONS ARE IN MILLIMETERS.

  B) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA & AB, DATED NOV. 1999.

  C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

  D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.

  E) DIMENSIONS L3,0,E1&D1 TABLE:

	.,	0.0.10 20,0	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	
		OPTION AA	OPTION AB	
[	L3	0.89-1.27	1.52-2.03	
ı	D	5.97-6.22	5.33-5.59	
	E1	4.32 MIN	3.81 MIN	
	0.1	E OI MIN	4 5 7 1 4411	

E1 4.32 MIN 3.01 MIN
D1 5.21 MIN 4.57 MIN
PRESENCE OF TRIMMED CENTER LEAD
IS OPTIONAL.

Dimensions in Millimeters



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Definition of Terms					
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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.			
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.			
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.			

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